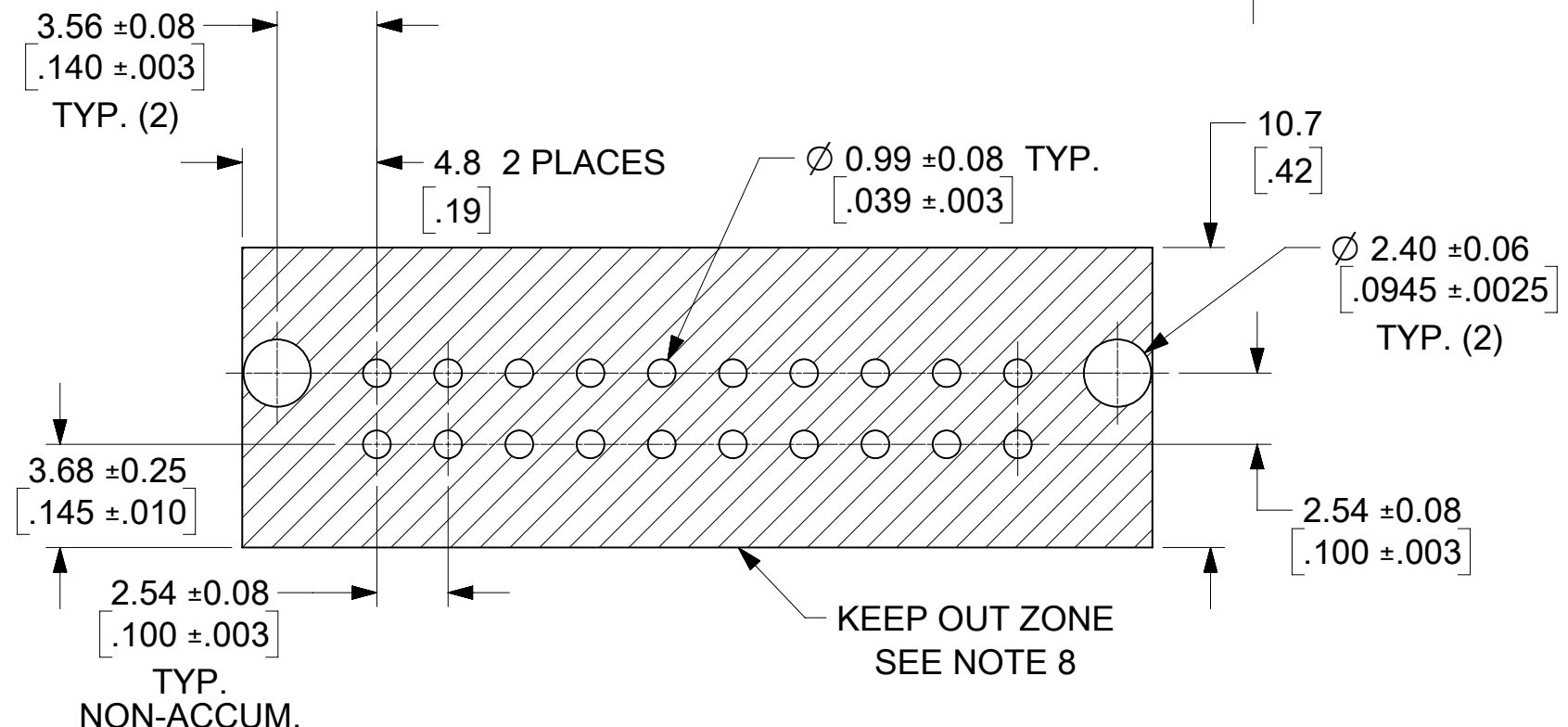
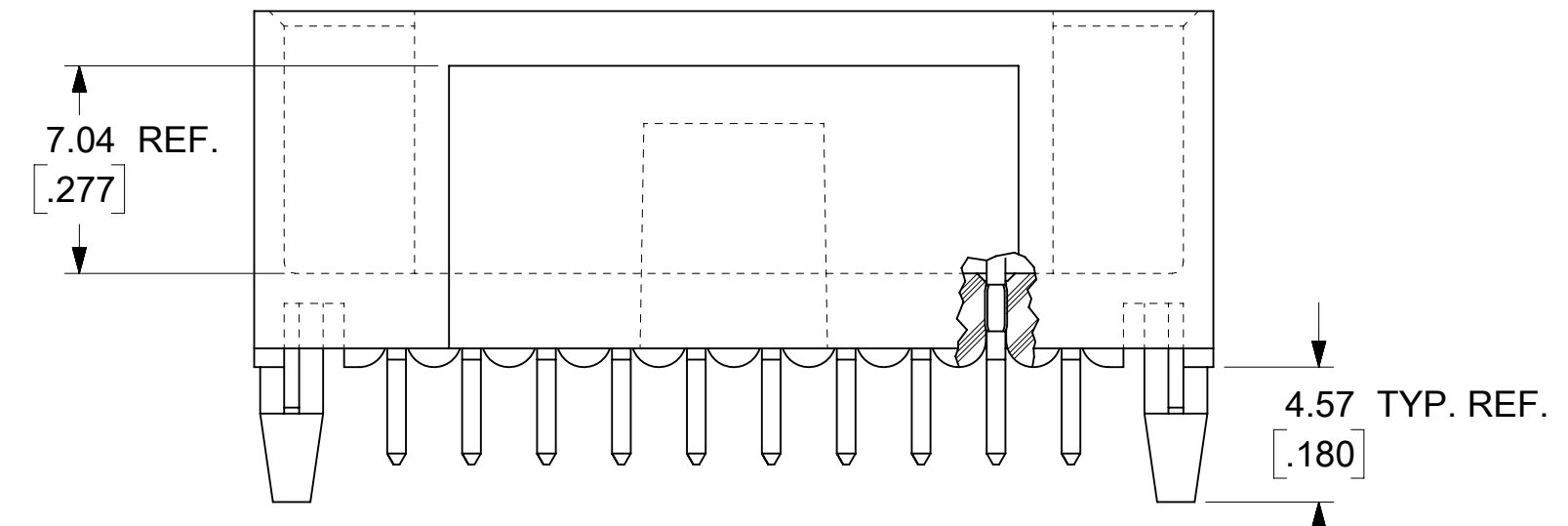
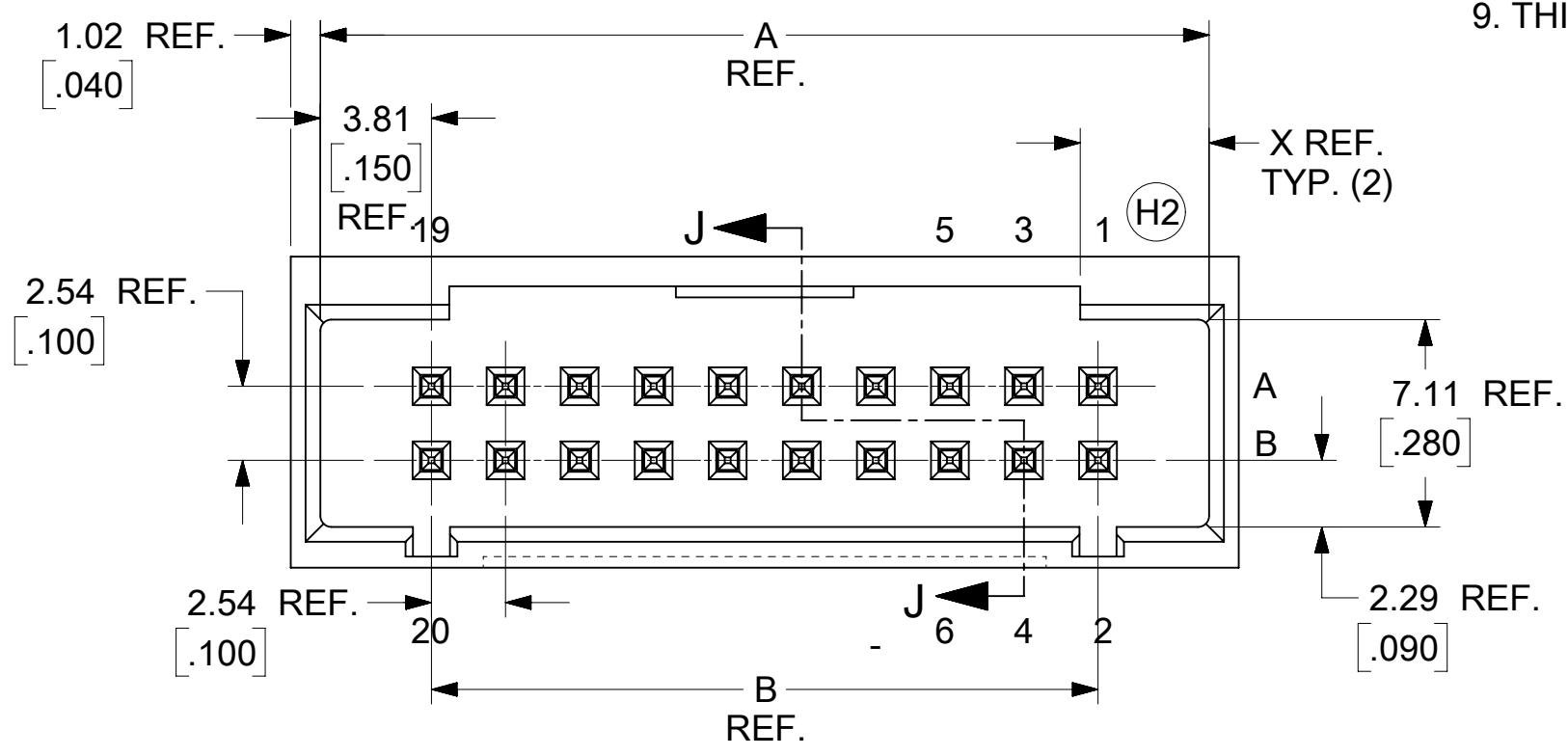
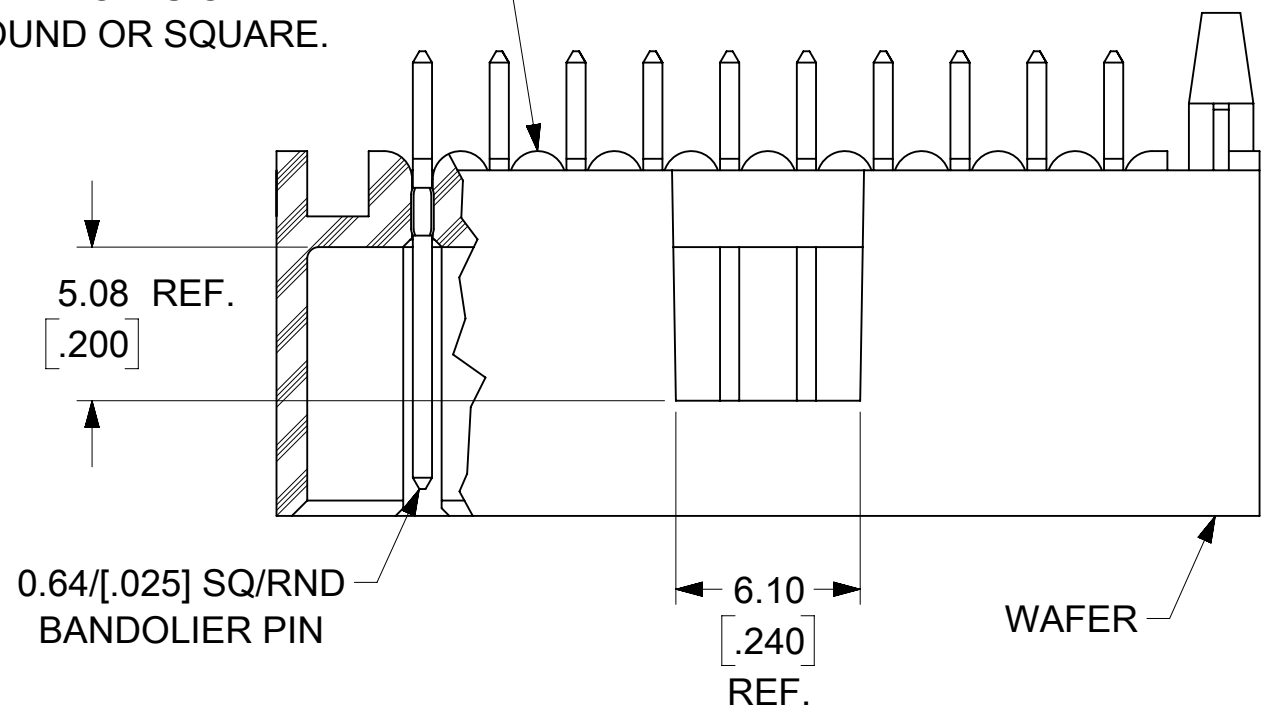


STAND OFFS CAN BE EITHER ROUND OR SQUARE.

NOTES:

- MATERIAL: WAFER - GLASS FILLED LIQUID CRYSTAL POLYMER; UL 94V-0; COLOR: BLACK. PIN: COPPER ALLOY.
- PLATING: TIN
TIN(Sn) ALLOY OVER ENTIRE PIN: THICKNESS = 3.81 MICROMETER/ [150 MICROINCH] MINIMUM;
NICKEL (Ni) UNDERPLATE OVER ENTIRE PIN.
15 GOLD SELECTIVE GOLD (Au) IN THE CONTACT AREA: THICKNESS = 0.38MICROMETER/ [15 MICROINCH] MINIMUM;
SELECTIVE TIN (Sn) ALLOY IN THE PC TAIL AREA: THICKNESS = 1.91 MICROMETER/ [75 MICROINCH] MINIMUM;
NICKEL (Ni) UNDERPLATE OVER ENTIRE PIN.
30 GOLD SELECTIVE GOLD (Au) IN THE CONTACT AREA: THICKNESS = 0.76 MICROMETER/ [30 MICROINCH] MINIMUM;
SELECTIVE TIN (Sn) ALLOY IN THE PC TAIL AREA: THICKNESS = 1.91 MICROMETER/ [75 MICROINCH] MINIMUM;
NICKEL (Ni) UNDERPLATE OVER ENTIRE PIN.
* THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".
CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD.
- PRODUCT SPECIFICATION: PS-70567.
- PACKAGING: SEE CHARTS
- PIN PUSHOUT FORCE: 4 LS. MIN. IN DIRECTION INDICATED.
- FOR ILLUSTRATION PURPOSES, 20 (DUAL 10) CIRCUIT SIZE IS SHOWN.
- PINS MUST MEET SOLDERABILITY SPEC. SMES-152,
EXCEPT VOIDS ARE PERMISSIBLE AT BANDOLIER PIN FAYING SURFACE. (APPROX. 0.64/[.025] LNG X 0.15/[.006] WD. REF.) - 2 LOCATIONS
- NO FEATURES WHICH RISE ABOVE THE PCB SURFACE ALLOWED IN THIS AREA.
- THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPEC PS-45499-002.



CKT. SIZE	DIM. A REF.		DIM. B REF.		DIM. X REF.	
	MM	INCH	MM	INCH	MM	INCH
6	12.70	.500	5.08	.200	3.18	.125
8	15.24	.600	7.62	.300	4.42	.174
10	17.78	.700	10.16	.400	4.42	.174
12	20.32	.800	12.70	.500	4.42	.174
14	22.86	.900	15.24	.600	4.42	.174
16	25.40	1.000	17.78	.700	4.42	.174
18	27.94	1.100	20.32	.800	4.42	.174
20	30.48	1.200	22.86	.900	4.42	.174
22	33.02	1.300	25.40	1.000	4.42	.174
24	35.56	1.400	27.94	1.100	4.42	.174
26	38.10	1.500	30.48	1.200	4.42	.174
28	40.64	1.600	33.02	1.300	4.42	.174
30	43.18	1.700	35.56	1.400	4.42	.174
32	45.72	1.800	38.10	1.500	4.42	.174
34	48.26	1.900	40.64	1.600	4.42	.174
36	50.80	2.000	43.18	1.700	4.42	.174
38	53.34	2.100	45.72	1.800	4.42	.174
40	55.88	2.200	48.26	1.900	4.42	.174
42	58.42	2.300	50.80	2.000	4.42	.174
44	60.96	2.400	53.34	2.100	4.42	.174
46	63.50	2.500	55.88	2.200	4.42	.174
48	66.04	2.600	58.42	2.300	4.42	.174
50	68.58	2.700	60.96	2.400	4.42	.174
52	71.12	2.800	63.50	2.500	4.42	.174
54	73.66	2.900	66.04	2.600	4.42	.174
56	76.20	3.000	68.58	2.700	4.42	.174
58	78.74	3.100	71.12	2.800	4.42	.174
60	81.28	3.200	73.66	2.900	4.42	.174
62	83.82	3.300	76.20	3.000	4.42	.174
64	86.36	3.400	78.74	3.100	4.42	.174
66	88.90	3.500	81.28	3.200	4.42	.174
68	91.44	3.600	83.82	3.300	4.42	.174
70	93.98	3.700	86.36	3.400	4.42	.174
72	96.52	3.800	88.90	3.500	4.42	.174

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

DIMENSION UNITS	SCALE	CURRENT REV DESC: CIRCUIT POSITIONS	molex
mm/[in]	4:1	STATEMENT UPDATED AS PER A-70568-XXXX DRAWING	
GENERAL TOLERANCES (UNLESS SPECIFIED)		EC NO: 676771	SALES ASSY - DUAL ROW SHROUDED WAFER/HI TEMP .25SQ/RND PINS .100 GRID
4 PLACES	±	DRWN: RMV02	2021/09/02
3 PLACES	±	CHK'D: KCHIKKANNA	2021/09/08
2 PLACES	± 0.13	APPR: ISHWARG	2021/10/14
1 PLACE	± 0.25	INITIAL REVISION:	
0 PLACES	±	DRWN: SMR	1993/11/10
ANGULAR TOL	± 0.5°	APPR:	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIRD ANGLE PROJECTION	DRAWING	SERIES
		C-SIZE	70568
DOCUMENT STATUS	P1	RELEASE DATE	2021/10/14 14:42:29
		DOCUMENT NUMBER	SDA-70568-XXXX
		DOC TYPE	PSD
		DOC PART	001
		REVISION	H2
		MATERIAL NUMBER	SEE TABLE
		CUSTOMER	GENERAL MARKET
		SHEET NUMBER	1 OF 2

